

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau



162162



(43) International Publication Date
18 July 2002 (18.07.2002)

PCT

(10) International Publication Number
WO 02/056031 A1

(51) International Patent Classification⁷: **G01P 15/08**,
H01L 21/822, 23/04

(21) International Application Number: PCT/AU02/00013

(22) International Filing Date: 8 January 2002 (08.01.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
PR 2453 10 January 2001 (10.01.2001) AU

(71) Applicant (for all designated States except US): **SILVERBROOK RESEARCH PTY. LTD.** [AU/AU]; 393 Darling Street, Balmain, New South Wales 2041 (AU).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **SILVERBROOK, KIA** [AU/AU]; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, New South Wales 2041 (AU).

(74) Agent: **SILVERBROOK, Kia**; Silverbrook Research Pty Ltd, 393 Darling Street, Balmain, New South Wales 2041 (AU).

(81) Designated States (*national*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CII, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZM, ZW.

(84) Designated States (*regional*): ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

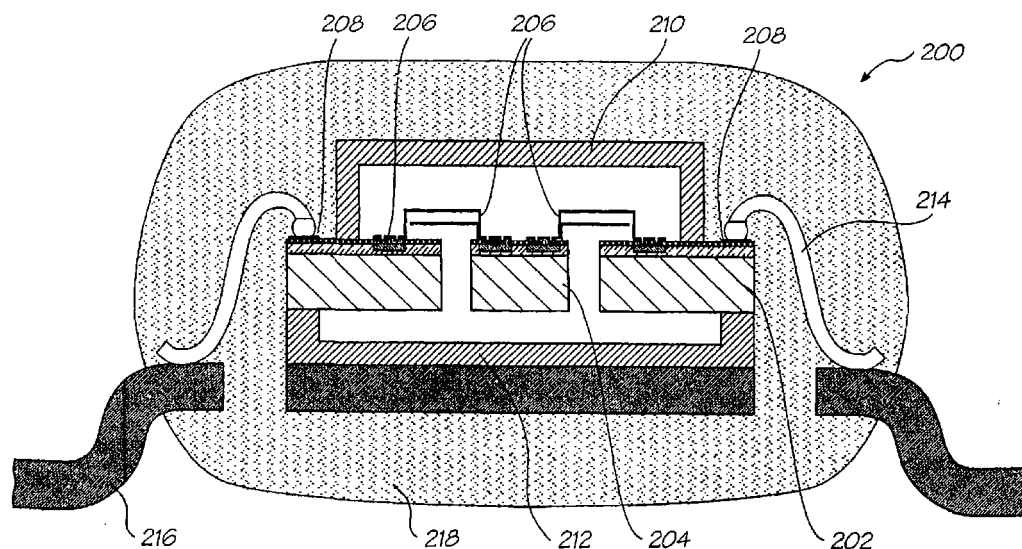
— with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.



G00002

(54) Title: ACCELEROMETER PROTECTED BY CAPS APPLIED AT THE WAFER SCALE



(57) Abstract: An accelerometer chip (202) has a molded thermoplastic cap (210) applied on one surface to provide a cavity into which the cantilevered mass (204) of the accelerometer may move. An array of caps is applied to a wafer of accelerometer chips (202) before singulation of the wafer.

WO 02/056031 A1